ON Semiconductor

Initial Product/Process Change Notification

Document # : IPCN20966X
Issue Date: 14 July 2015

Title of Change:	Initial PCN for wafer fab expansion to Maxchip Electronics Corp. (MXP) in Taiwan.
Proposed first ship date:	21 November 2015
Contact information:	Contact your local ON Semiconductor Sales Office or <Yasuhiro.Igarashi@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office.
Type of notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.
Change Part Identification:	Affected products will be identified with date code.
Change category:	☒ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other _____

Change Sub-Category(s):

☒ Manufacturing Site Change/Addition
☐ Manufacturing Process Change
☐ Material Change
☐ Product specific change
☐ Datasheet/Product Doc change
☐ Shipping/Packaging/Marking
☐ Other: _____

Sites Affected:

☐ All site(s) ☐ not applicable
☐ ON Semiconductor site(s)
☒ External Foundry/Subcon site(s)
Maxchip Electronics Corp.

Description and Purpose:

This is an Initial Process Change Notification to announce the addition of Maxchip Electronics Corp (MXP) as a wafer fabrication site for the listed ON Semiconductor products. MXP is located in Hsinchu, Taiwan, and is ISO9001 certified.

The product design and electrical specifications will not change. A full electrical characterization over the temperature range will be performed for each product to check the device functionality and electrical specifications. Qualification tests are designed to show that the reliability of the affected products will continue to meet or exceed ON Semiconductor standards.

Qualification Plan:

Estimated date for qualification completion: 25 September 2015

Test:	Conditions:	Interval:	Unit:	Lot:
AC(AUTOCLAVE)	121°C, RH=100%,15psig	96Hrs	77pcs	3lots
H3TRB(High Temperature High Humidity Reverse Bias)	85°C, RH=85%,VDSS=24V	1008Hrs	77pcs	3 lots
HTGB(High Temperature Reverse Gate Bias)	Ta=150°C, VGSS=12.5V	1008Hrs	77pcs	3 lots
HTRB(High Temperature Reverse Bias)	Ta=150°C, VDSS=24V	1008Hrs	77pcs	3 lots
HTSL(High Temperature Storage Life)	Ta=150°C	1008Hrs	77pcs	3 lots
IOL(Intermittent Operational Life)	Ta=25°C,ΔTj=100°C	15000cycles	77pcs	3 lots
RS(Resistance to Solvent)	Ta=260°C		30pcs	3 lots
TC(Temperature Cycling)	Ta=-55°C to 150°C	500cycles	77pcs	3 lots

List of Affected Standard Parts:

Part Number	Qualification Vehicle
ECH8693R-TL-W	ECH8693R-TL-W
ECH8695R-TL-W	ECH8693R-TL-W
ECH8697R-TL-W	ECH8693R-TL-W